



Material Content Data Sheet



Sales Product Name		BGSA 13GN10 E6327		Issued		19. July 2018		
MA#		MA001264208						
Package		PG-TSNP-10-1		Weight*		1.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.352	18.62	18.62	186246	186246
bumps	non noble metal	copper	7440-50-8	0.005	0.27	0.27	2667	2667
leadframe	non noble metal	tin	7440-31-5	0.002	0.09		891	
	non noble metal	zinc	7440-66-6	0.001	0.07		713	
	non noble metal	chromium	7440-47-3	0.002	0.11		1069	
encapsulation	non noble metal	copper	7440-50-8	0.669	35.37	35.64	353710	356383
	organic material	carbon black	1333-86-4	0.004	0.21		2145	
	plastics	epoxy resin	-	0.118	6.22		62196	
	inorganic material	silicondioxide	60676-86-0	0.689	36.47	42.90	364595	428936
leadfinish	non noble metal	tin	7440-31-5	0.029	1.52	1.52	15230	15230
plating	noble metal	silver	7440-22-4	0.017	0.91	0.91	9070	9070
solder	noble metal	silver	7440-22-4	0.000	0.00		34	
	non noble metal	tin	7440-31-5	0.003	0.14	0.14	1434	1468
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com